

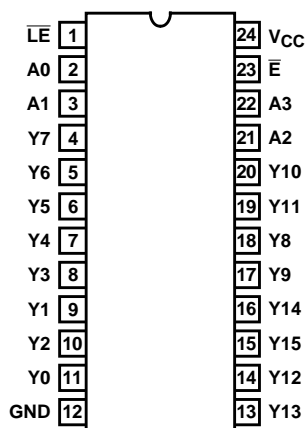
## High-Speed CMOS Logic 4- to 16-Line Decoder/Demultiplexer with Input Latches

### Features

- Multifunction Capability
  - Binary to 1-of-16 Decoder
  - 1-to-16 Line Demultiplexer
- Fanout (Over Temperature Range)
  - Standard Outputs . . . . . 10 LSTTL Loads
  - Bus Driver Outputs . . . . . 15 LSTTL Loads
- Wide Operating Temperature Range . . . -55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types
  - 2V to 6V Operation
  - High Noise Immunity:  $N_{IL} = 30\%$ ,  $N_{IH} = 30\%$  of  $V_{CC}$  at  $V_{CC} = 5V$

### Pinout

CD54HC4514  
(CERDIP)  
CD74HC4514, CD74HC4515  
(PDIP, SOIC)  
TOP VIEW



### Description

The CD54HC4514, CD74HC4514, and CD74HC4515 are high-speed silicon gate devices consisting of a 4-bit strobed latch and a 4- to 16-line decoder. The selected output is enabled by a low on the enable input (E). A high on  $\bar{E}$  inhibits selection of any output. Demultiplexing is accomplished by using the  $\bar{E}$  input as the data input and the select inputs (A0-A3) as addresses. This  $\bar{E}$  input also serves as a chip select when these devices are cascaded.

When Latch Enable ( $\overline{LE}$ ) is high the output follows changes in the inputs (see truth table). When  $\overline{LE}$  is low the output is isolated from changes in the input and remains at the level (high for the 4514, low for the 4515) it had before the latches were enabled. These devices, enhanced versions of the equivalent CMOS types, can drive 10 LSTTL loads.

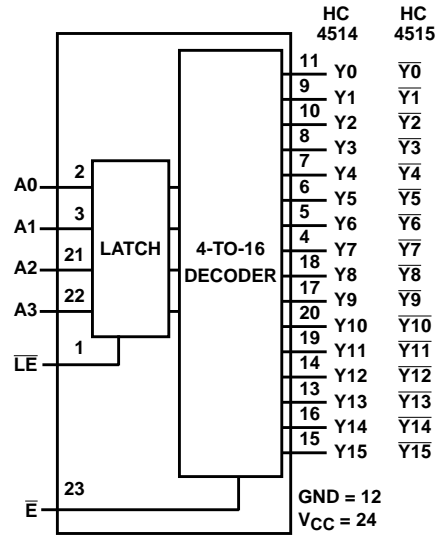
### Ordering Information

PART NUMBER	TEMP. RANGE (°C)	PACKAGE
CD54HC4514F3A	-55 to 125	24 Ld CERDIP
CD74HC4514E	-55 to 125	24 Ld PDIP
CD74HC4514EN	-55 to 125	24 Ld PDIP
CD74HC4514M	-55 to 125	24 Ld SOIC
CD74HC4514M96	-55 to 125	24 Ld SOIC
CD74HC4515E	-55 to 125	24 Ld PDIP
CD74HC4515EN	-55 to 125	24 Ld PDIP
CD74HC4515M	-55 to 125	24 Ld SOIC
CD74HC4515M96	-55 to 125	24 Ld SOIC

NOTE: When ordering, use the entire part number. The suffix 96 denotes tape and reel.

# CD54HC4514, CD74HC4514, CD74HC4515

## Functional Diagram



DECODE TRUTH TABLE ( $\overline{LE} = 1$ )

ENABLE	DECODER INPUTS				ADDRESSED OUTPUT 4514 = LOGIC 1 (HIGH) 4515 = LOGIC 0 (HIGH)
	A3	A2	A1	A0	
0	0	0	0	0	Y0
0	0	0	0	1	Y1
0	0	0	1	0	Y2
0	0	0	1	1	Y3
0	0	1	0	0	Y4
0	0	1	0	1	Y5
0	0	1	1	0	Y6
0	0	1	1	1	Y7
0	1	0	0	0	Y8
0	1	0	0	1	Y9
0	1	0	1	0	Y10
0	1	0	1	1	Y11
0	1	1	0	0	Y12
0	1	1	0	1	Y13
0	1	1	1	0	Y14
0	1	1	1	1	Y15
1	X	X	X	X	All Outputs = 0, 4514 All Outputs = 1, 4515

X = Don't Care; Logic 1 = High; Logic 0 = Low

# CD54HC4514, CD74HC4514, CD74HC4515

## Absolute Maximum Ratings

DC Supply Voltage, $V_{CC}$	-0.5V to 7V
DC Input Diode Current, $I_{IK}$	
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$	$\pm 20mA$
DC Output Diode Current, $I_{OK}$	
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$	$\pm 20mA$
DC Drain Current, per Output, $I_O$	
For $-0.5V < V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC Output Source or Sink Current per Output Pin, $I_O$	
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$	$\pm 25mA$
DC $V_{CC}$ or Ground Current, $I_{CC}$	$\pm 50mA$

## Thermal Information

Thermal Resistance (Typical)	$\theta_{JA}$ ( $^{\circ}C/W$ )
E (PDIP) Package (Note 1)	67
EN (PDIP) Package (Note 1)	67
M (SOIC) Package (Note 2)	46
Maximum Junction Temperature	150 $^{\circ}C$
Maximum Storage Temperature Range	-65 $^{\circ}C$ to 150 $^{\circ}C$
Maximum Lead Temperature (Soldering 10s)	300 $^{\circ}C$
(SOIC - Lead Tips Only)	

## Operating Conditions

Temperature Range ( $T_A$ )	-55 $^{\circ}C$ to 125 $^{\circ}C$
Supply Voltage Range, $V_{CC}$	
HC Types	2V to 6V
DC Input or Output Voltage, $V_I$ , $V_O$	0V to $V_{CC}$
Input Rise and Fall Time	
2V	1000ns (Max)
4.5V	500ns (Max)
6V	400ns (Max)

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### NOTES:

1. The package thermal impedance is calculated in accordance with JESD 51-3.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## DC Electrical Specifications

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES												
High Level Input Voltage	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
				4.5	3.15	-	-	3.15	-	3.15	-	V
				6	4.2	-	-	4.2	-	4.2	-	V
Low Level Input Voltage	V <sub>IL</sub>	-	-	2	-	-	0.5	-	0.5	-	0.5	V
				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output Voltage CMOS Loads	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
-			-	-	-	-	-	-	-	-	V	
-4			4.5	3.98	-	-	3.84	-	3.7	-	V	
-5.2			6	5.48	-	-	5.34	-	5.2	-	V	
High Level Output Voltage TTL Loads												

# CD54HC4514, CD74HC4514, CD74HC4515

## DC Electrical Specifications (Continued)

PARAMETER	SYMBOL	TEST CONDITIONS		V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
		V <sub>I</sub> (V)	I <sub>O</sub> (mA)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
Low Level Output Voltage CMOS Loads	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
			0.02	6	-	-	0.1	-	0.1	-	0.1	V
-			-	-	-	-	-	-	-	-	V	
Low Level Output Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	I <sub>I</sub>	V <sub>CC</sub> or GND	-	6	-	-	±0.1	-	±1	-	±1	μA
Quiescent Device Current	I <sub>CC</sub>	V <sub>CC</sub> or GND	0	6	-	-	8	-	80	-	160	μA

## Prerequisite For Switching Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
$\overline{\text{LE}}$ Pulse Width	$t_W$	-	2	75	-	-	95	-	110	-	ns
			4.5	30	-	-	19	-	22	-	ns
			6	35	-	-	16	-	19	-	ns
Select to $\overline{\text{LE}}$ Set-Up Time	$t_{\text{SU}}$	-	2	100	-	-	125	-	150	-	ns
			4.5	20	-	-	25	-	30	-	ns
			6	17	-	-	21	-	26	-	ns
Select to $\overline{\text{LE}}$ Hold Time	$t_H$	-	2	0	-	-	0	-	0	-	ns
			4.5	0	-	-	0	-	0	-	ns
			6	0	-	-	0	-	0	-	ns

## Switching Specifications C<sub>L</sub> = 50pF, Input t<sub>r</sub>, t<sub>f</sub> = 6ns

PARAMETER	SYMBOL	TEST CONDITIONS	V <sub>CC</sub> (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
HC TYPES											
Propagation Delay Select to Outputs	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	2	-	-	275	-	345	-	415	ns
			4.5	-	-	55	-	69	-	83	ns
		C <sub>L</sub> = 15pF	5	-	23	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	47	-	59	-	71	ns
LE to Outputs	t <sub>PHL</sub> , t <sub>PLH</sub>	C <sub>L</sub> = 50pF	2	-	-	225	-	280	-	340	ns
			4.5	-	-	45	-	56	-	68	ns
		C <sub>L</sub> = 15pF	5	-	19	-	-	-	-	-	ns
		C <sub>L</sub> = 50pF	6	-	-	38	-	48	-	58	ns

# CD54HC4514, CD74HC4514, CD74HC4515

## Switching Specifications $C_L = 50\text{pF}$ , Input $t_r, t_f = 6\text{ns}$ (Continued)

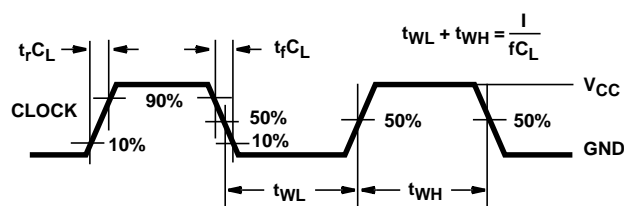
PARAMETER	SYMBOL	TEST CONDITIONS	$V_{CC}$ (V)	25°C			-40°C TO 85°C		-55°C TO 125°C		UNITS
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$\bar{E}$ to Outputs	$t_{PHL}, t_{PLH}$	$C_L = 50\text{pF}$	2	-	-	175	-	220	-	265	ns
			4.5	-	-	35	-	44	-	53	ns
		$C_L = 15\text{pF}$	5	-	14	-	-	-	-	-	ns
		$C_L = 50\text{pF}$	6	-	-	30	-	37	-	45	ns
Output Transition Time	$t_{THL}, t_{TLH}$	$C_L = 50\text{pF}$	2	-	-	75	-	95	-	110	ns
			4.5	-	-	15	-	19	-	22	ns
			6	-	-	13	-	16	-	19	ns
Input Capacitance	$C_{IN}$	$C_L = 50\text{pF}$	-	10	-	10	-	10	-	10	pF
Power Dissipation Capacitance (Notes 3, 4)	$C_{PD}$	-	5	-	70	-	-	-	-	-	pF

### NOTES:

3.  $C_{PD}$  is used to determine the dynamic power consumption, per package.

4.  $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$  where  $f_i$  = Input Frequency,  $C_L$  = Output Load Capacitance,  $V_{CC}$  = Supply Voltage.

## Test Circuits and Waveforms



NOTE: Outputs should be switching from 10%  $V_{CC}$  to 90%  $V_{CC}$  in accordance with device truth table. For  $f_{MAX}$ , input duty cycle = 50%.

FIGURE 1. HC CLOCK PULSE RISE AND FALL TIMES AND PULSE WIDTH

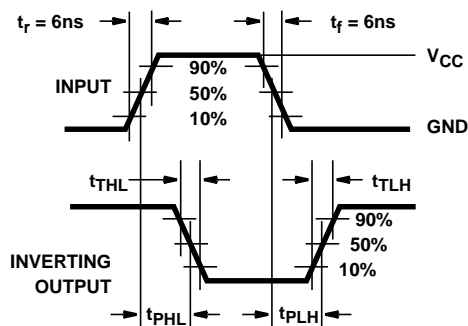


FIGURE 2. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

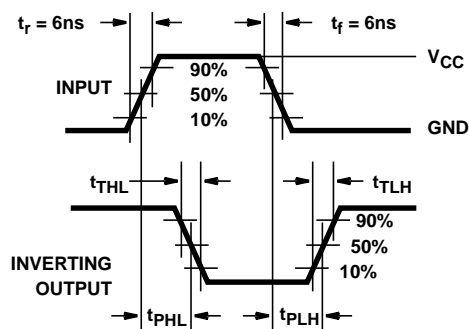


FIGURE 3. HC TRANSITION TIMES AND PROPAGATION DELAY TIMES, COMBINATION LOGIC

**Test Circuits and Waveforms** (Continued)

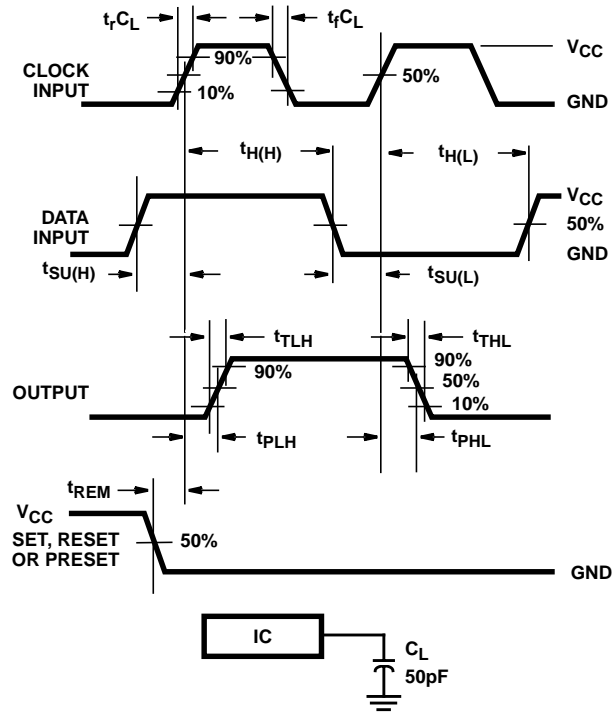


FIGURE 4. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

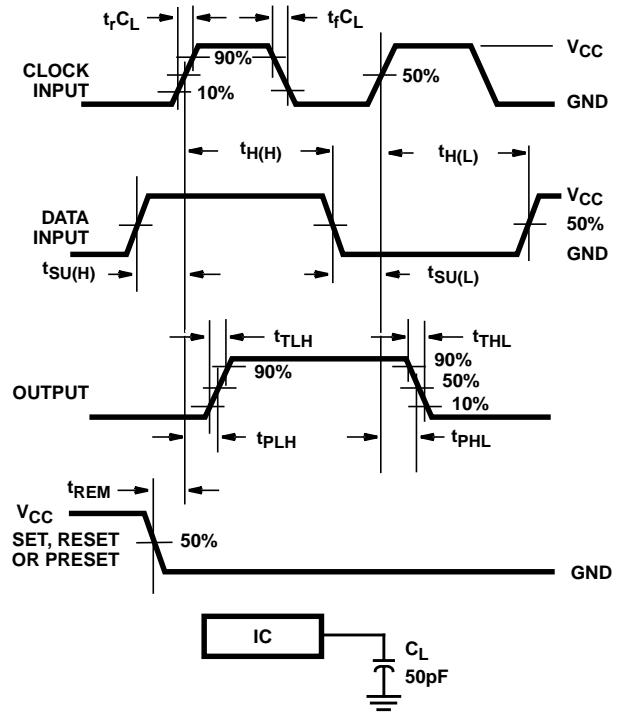


FIGURE 5. HC SETUP TIMES, HOLD TIMES, REMOVAL TIME, AND PROPAGATION DELAY TIMES FOR EDGE TRIGGERED SEQUENTIAL LOGIC CIRCUITS

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">5962-9865501QJA</a>	Active	Production	CDIP (J)   24	15   TUBE	No	Call TI	N/A for Pkg Type	-55 to 125	5962-9865501QJ A CD54HC4514F3A
<a href="#">CD54HC4514F3A</a>	Active	Production	CDIP (J)   24	15   TUBE	No	Call TI	N/A for Pkg Type	-55 to 125	5962-9865501QJ A CD54HC4514F3A
CD54HC4514F3A.A	Active	Production	CDIP (J)   24	15   TUBE	No	Call TI	N/A for Pkg Type	-55 to 125	5962-9865501QJ A CD54HC4514F3A
<a href="#">CD74HC4514M</a>	Obsolete	Production	SOIC (DW)   24	-	-	Call TI	Call TI	-55 to 125	HC4514M
<a href="#">CD74HC4514M96</a>	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4514M
CD74HC4514M96.A	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4514M
<a href="#">CD74HC4515M</a>	Obsolete	Production	SOIC (DW)   24	-	-	Call TI	Call TI	-55 to 125	HC4515M
<a href="#">CD74HC4515M96</a>	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4515M
CD74HC4515M96.A	Active	Production	SOIC (DW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4515M

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF CD54HC4514, CD74HC4514 :**

- Catalog : [CD74HC4514](#)
- Military : [CD54HC4514](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications



## TAPE AND REEL INFORMATION



\*All dimensions are nominal

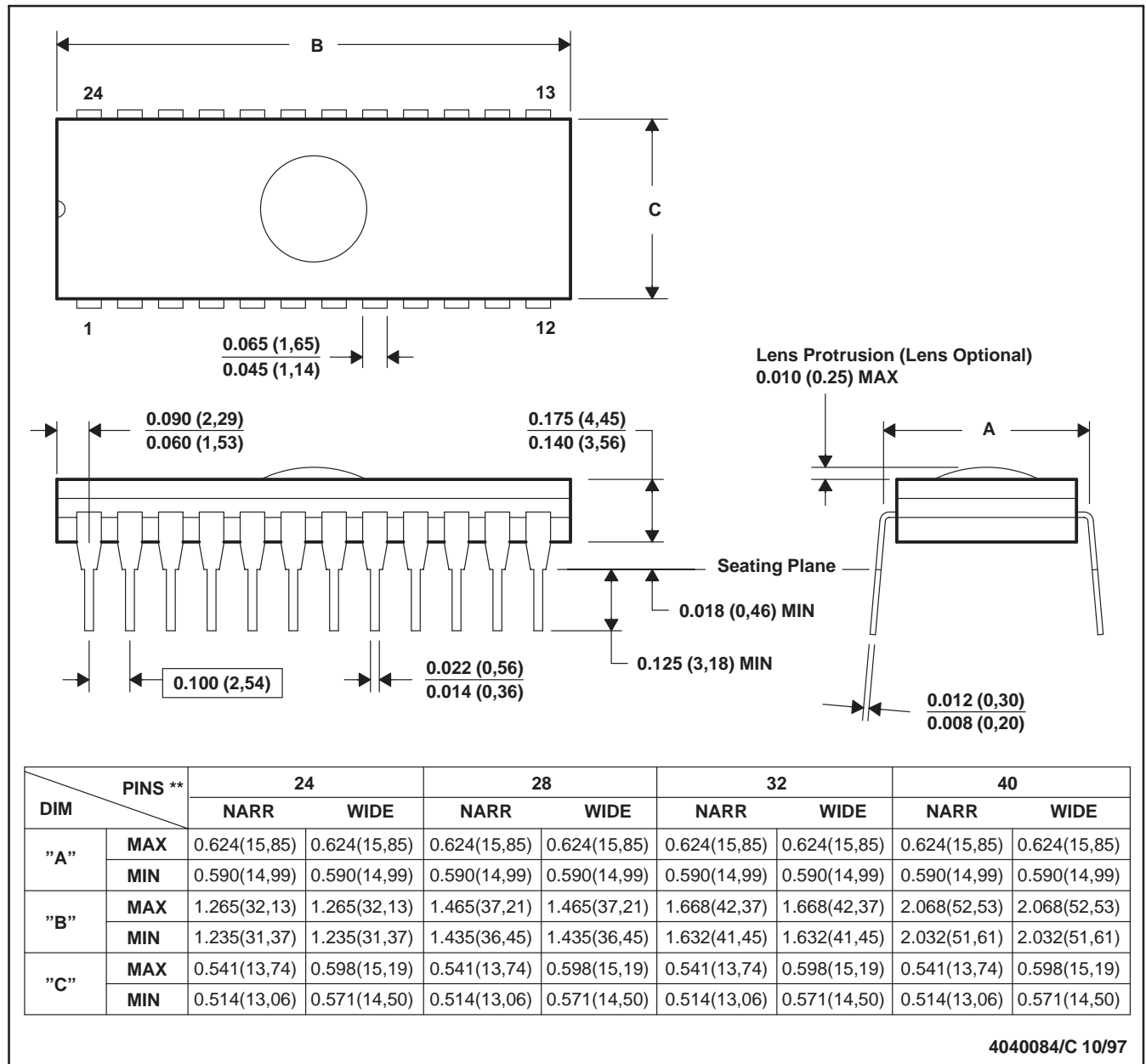
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4514M96	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
CD74HC4515M96	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

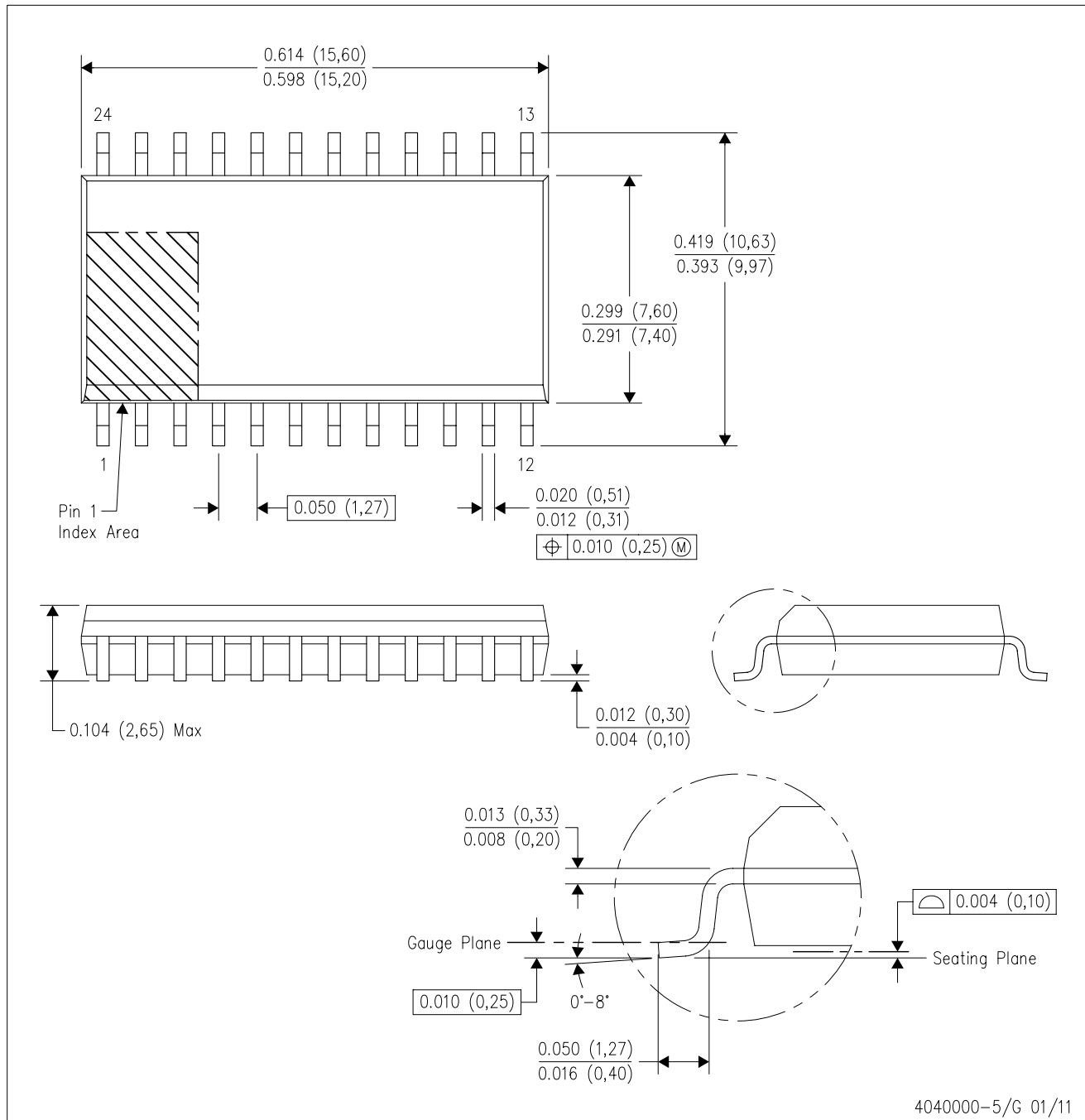
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4514M96	SOIC	DW	24	2000	350.0	350.0	43.0
CD74HC4515M96	SOIC	DW	24	2000	350.0	350.0	43.0

**J (R-GDIP-T\*\*)****CERAMIC DUAL-IN-LINE PACKAGE****24 PINS SHOWN**

- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Window (lens) added to this group of packages (24-, 28-, 32-, 40-pin).  
 D. This package can be hermetically sealed with a ceramic lid using glass frit.  
 E. Index point is provided on cap for terminal identification.

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AD.

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025